

# NCE P-Channel Enhancement Mode Power MOSFET

## Description

The NCE01P18L uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications. It is ESD protested.

## **General Features**

V<sub>DS</sub> =-100V,I<sub>D</sub> =-18A
 R<sub>DS(ON)</sub> <100mΩ @ V<sub>GS</sub>=-10V (Typ:85mΩ)
 R<sub>DS(ON)</sub> <120mΩ @ V<sub>GS</sub>=-10V (Typ:95mΩ)

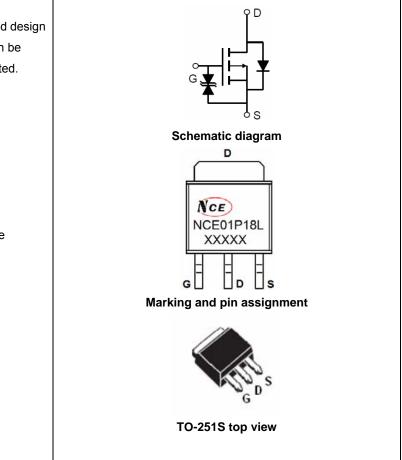
- Super high dense cell design
- Advanced trench process technology
- Reliable and rugged
- High density cell design for ultra low On-Resistance

#### Application

- Power management in notebook computer
- Portable equipment and battery powered systems

### 100% UIS TESTED!

#### 100% ΔVds TESTED!



## Package Marking and Ordering Information

1						
	Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
	NCE01P18L	NCE01P18L	TO-251S	-	-	-

## Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	-100	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	Ι <sub>D</sub>	-18	А
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100℃)	-12	A
Pulsed Drain Current	I <sub>DM</sub>	-100	A
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	170	mJ
Maximum Power Dissipation	PD	70	W
Derating factor		0.47	W/°C
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 175	°C

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Case (Note 2)	R <sub>θJc</sub>	2.14	°C/W	
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## Electrical Characteristics (T<sub>c</sub>=25<sup>°</sup>C unless otherwise noted)

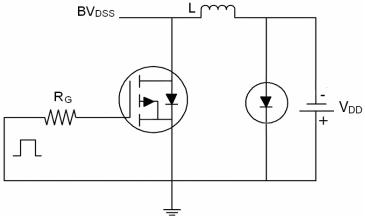
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250µA	-100	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-100V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±20	μA
On Characteristics (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250µA	-1	-1.9	-3	V
Drain Course On State Desistence	P	V <sub>GS</sub> =-10V, I <sub>D</sub> =-16A	-	85	100	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	$V_{GS}=-10V, I_{D}=-16A$ $V_{GS}=-4.5V, I_{D}=-16A$ $V_{DS}=-50V, I_{D}=-10A$ $V_{DS}=-50V, V_{GS}=0V,$ $F=1.0MHz$		95	120	
Forward Transconductance	<b>G</b> FS	V <sub>DS</sub> =-50V,I <sub>D</sub> =-10A	5	-	-	S
Dynamic Characteristics (Note4)	·					
Input Capacitance	Clss	(-50)(1)(-0)(-0)(-0)(-0)(-0)(-0)(-0)(-0)(-0)(-0	-	3810	-	PF
Output Capacitance	Coss		-	129	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	125	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	16	-	nS
Turn-on Rise Time	tr	V <sub>DD</sub> =-50V,I <sub>D</sub> =-16A	-	73	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GS</sub> =-10V,R <sub>GEN</sub> =9.1Ω	-	34	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	57	-	nS
Total Gate Charge	Qg	N/ 50)// 40A	-	70	-	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =-50V,I <sub>D</sub> =-16A, V <sub>GS</sub> =-10V	-	12.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	v <sub>GS</sub> =-10v	-	15.5	-	nC
Drain-Source Diode Characteristics	·					
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-10A	-	-	-1.2	V
Diode Forward Current (Note 2)	Is	-	-	-	-18	А
Reverse Recovery Time	t <sub>rr</sub>	TJ = 25°C, IF =-16A	-	88.3	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs <sup>(Note3)</sup>	-	65.9	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negl	igible (turi	n-on is do	pminated b	y LS+LD)

#### Notes:

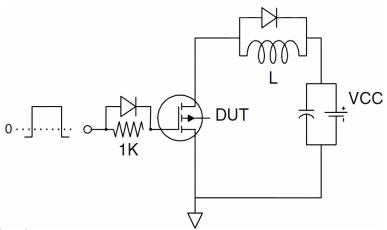
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition: Tj=25  $^\circ\!\mathrm{C}$  ,V\_{DD}=-50V,V\_G=-10V,L=0.5mH,Rg=25\Omega



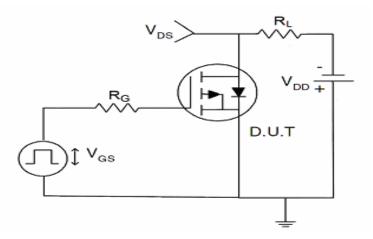
## Test Circuit 1) E<sub>AS</sub> Test Circuit



## 2) Gate Charge Test Circuit

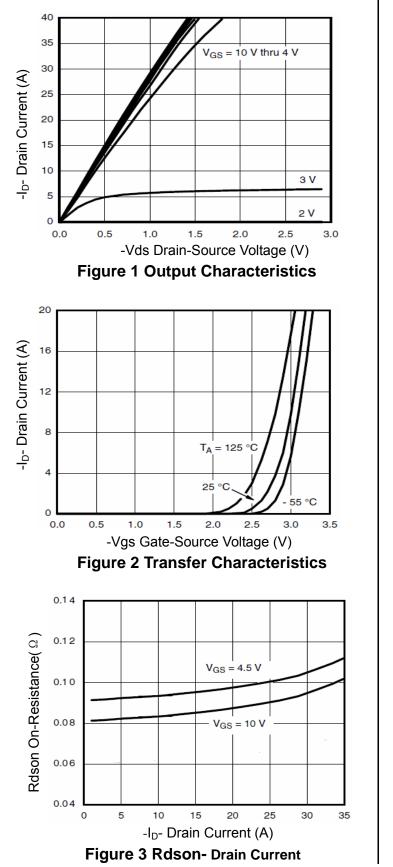


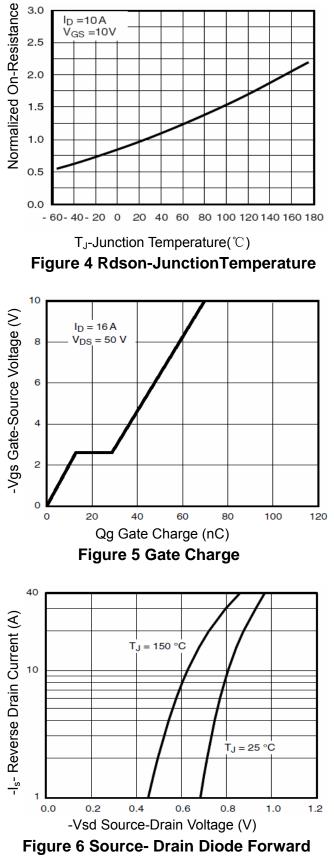
## 3) Switch Time Test Circuit





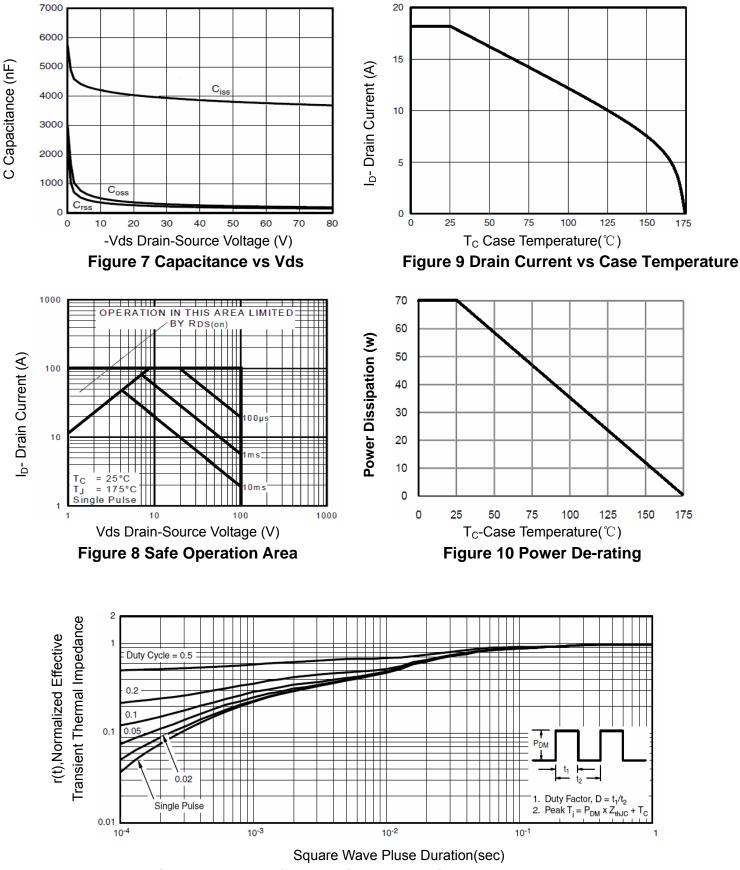
## **Typical Electrical and Thermal Characteristics (Curves)**







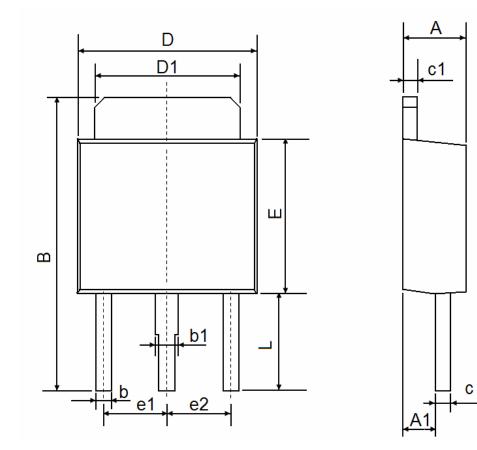
http://www.ncepower.com







# **TO-251S Package Information**



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	2.250	2.350	0.089	0.093	
A1	1.150	1.250	0.045	0.049	
В	10.200	10.800	0.402	0.425	
b	0.550	0.650	0.022	0.026	
b1	0.750	0.850	0.030	0.033	
С	0.480	0.540	0.019	0.021	
c1	0.480	0.540	0.019	0.021	
D	6.400	6.600	0.252	0.260	
D1	5.250	5.350	0.207	0.211	
E	5.400	5.600	0.213	0.220	
e1	2.300 TYP		0.091	0.091 TYP	
e2	2.300 TYP		0.091 TYP		
L	3.300	3.700	0.130	0.146	



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